

**FOR ADDITIONAL INFORMATION
CONTACT:**

Taylor Farrell.
Phone: (518) 452-2880
E-mail: tfarrell@yincae.com



YINCAE Advanced Materials, LLC
19 Walker Way, Albany, NY 12205
(518) 452-2880
www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

YINCAE President, Dr. Wusheng Yin, to Speak at IMAPS 2014

(Albany, NY) September 9, 2014. Dr. Wusheng Yin, the president of YINCAE Advanced Materials LLC, is going to be speaking at the upcoming IMAPS 2014 conference. IMAPS 2014 will take place from October 14th to 16th. It will be held at the Town & Country Resort and Conference Center in San Diego California.

Dr. Yin will be presenting his white paper, "*SOLDERABLE ANISOTROPIC CONDUCTIVE ADHESIVES FOR 3D PACKAGE APPLICATIONS*". This paper will focus on the trend of increased usage of 3D packaging and how the implementation 3D packaging is changing the electronics industry. The paper discusses how YINCAE is able to deal with these changes through developed products like the solderable anisotropic adhesive for 3D package applications. Dr. Yin will be also talking about the other groundbreaking products that YINCAE has developed and are commercially available.

YINCAE Advanced Materials, LLC hopes that you will come join us at the conference to learn about YINCAE and the products that we have to offer. YINCAE has exclusive products that no other company has developed. There is a lot that can be taken away from not only Dr.

MORE...

Yin's presentation, but from IMAPS 2014 as a whole. YINCAE hopes to see you there at the IMAPS 2014. Please visit us at booth 326!

Dr. Yin is a pioneer in the field of encapsulant adhesives and has developed several encapsulant products that have been successfully adopted by major microelectronics product and contract manufacturers. His encapsulant products have solved a number of technical issues related to microchip solder joint strength, uniformity and thermocycling. Tests comparing flux in nitrogen versus encapsulants in normal air flow have demonstrated that encapsulants can increase pull strength by 5 times while reducing thermal cycling failures by 10 times, with a reduction in solder voids of up to 79%. This data translates to significant production savings for microelectronics manufacturers.

If you wish to read the white paper "*SOLDERABLE ANISOTROPIC CONDUCTIVE ADHESIVES FOR 3D PACKAGE APPLICATIONS*", please click the following link: [White Paper](#)

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: [YINCAE Website](#).

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YINCAE Advanced Materials, LLC is a leading manufacturer and supplier of high-performance coatings, adhesives and encapsulants used in the computer microchip and optoelectronics industries. Our manufacturing operations and headquarters are located in Albany, NY USA, with technical sales and support available through a worldwide sales and service organization.

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